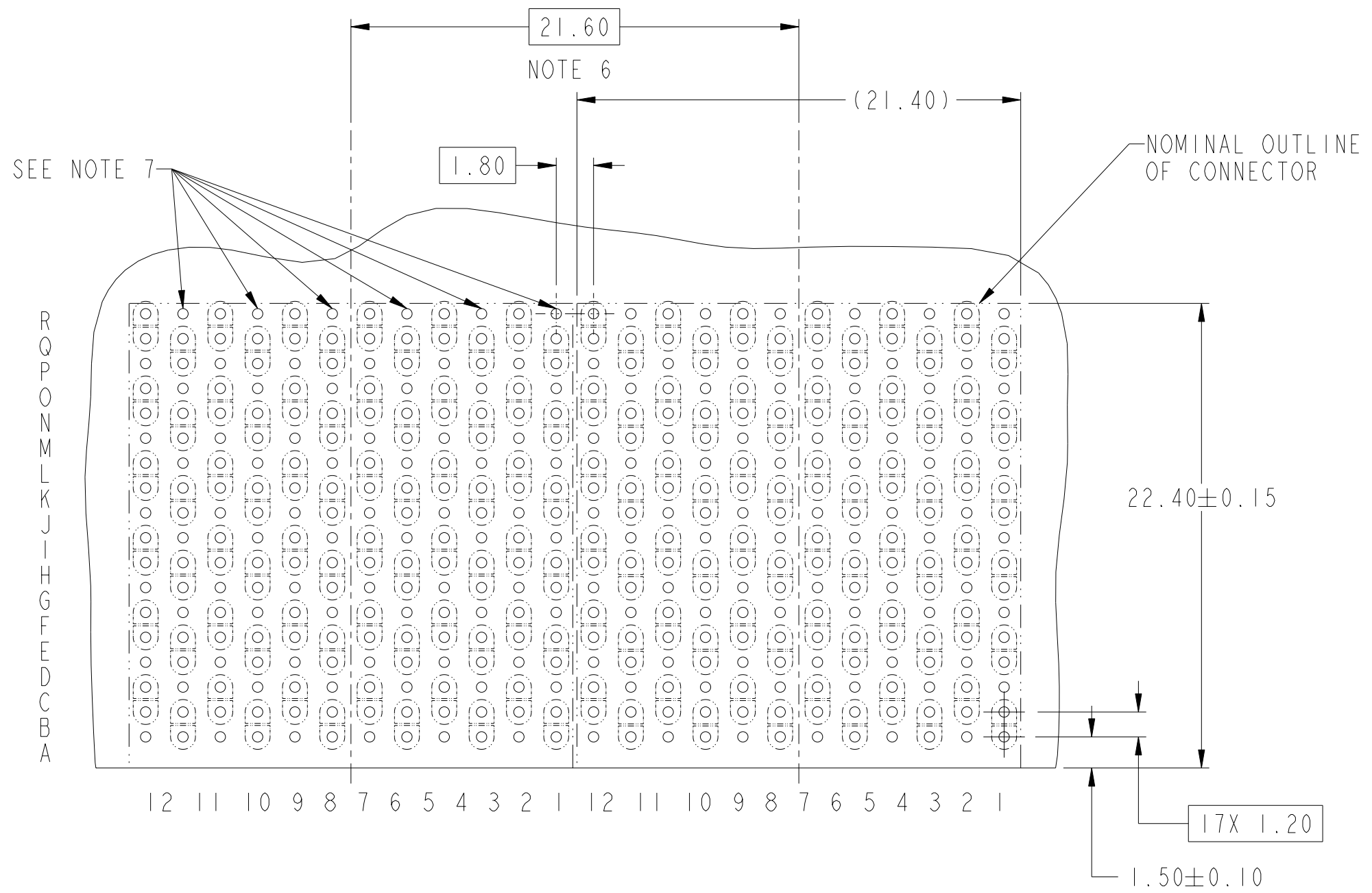






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RECOMMENDED PCB LAYOUT  
 FOR DIFFERENTIAL APPLICATIONS  
 COMPONENT SIDE  
 (TWO ADJACENT FOOTPRINTS SHOWN)  
 NOTES 6, 7, & 8

	title	ZipLine R/A REC ASSY	dwg no	10076209	Rev.	A
	catalog no	6 PR, 12 IMLA, 1.8MM PITCH, 21.6MM	-	CUSTOMER	sheet 2 of 3	

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1

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3

4

PRODUCT NUMBER	PLATING TYPE
10076209-101	TIN/LEAD ALLOY OVER NICKEL
10076209-101LF	TIN OVER NICKEL (LEAD FREE)

A

① - CONNECTOR MATERIALS:  
HOUSING: HIGH TEMP THERMOPLASTIC, BLACK, UL94-V0  
IMLA PLASTIC: HIGH TEMP THERMOPLASTIC, BLACK, UL94-V0  
CONTACT: COPPER ALLOY  
ORGANIZER: STAINLESS STEEL

2 - CONTACT PLATING:  
SEPARABLE INTERFACE:  
PERFORMANCE-BASED PLATING, QUALIFIED TO MEET THE REQUIREMENTS OF FCI PRODUCT SPECIFICATION GS-12-452 INCLUDING TELCORDIA GR-1217-CORE (NOVEMBER 1995) CENTRAL OFFICE TEST SEQUENCE

PRESS-FIT TAILS: SEE TABLE

3 - PRODUCT SPECIFICATION: GS-12-452

4 - APPLICATION SPECIFICATION: GS-20-094

⑤ - PRODUCT MARKING, (PART NUMBER & LOT CODE), ON THIS SURFACE.

⑥ - THE MINIMUM CENTERLINE SPACING BETWEEN ADJACENT MODULES IS 21.6MM.

⑦ - THERE IS NO GROUND BUSSING WITHIN THE CONNECTOR EXCEPT FOR POSITIONS R1, R3, R5, R7, R9, & R11. THESE MUST BE ASSIGNED AS GROUNDS.

⑧ - REFER TO CUSTOMER DRAWING 10045979 FOR INFORMATION ON PCB HOLE DIAMETERS AND PLATING OPTIONS

9 - LEAD FREE PRODUCT MEETS THE EUROPEAN UNION DIRECTIVES & OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008

10 - THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 40 SECONDS IN A CONVECTION, INFRA-RED, OR VAPOR PHASE REFLOW OVEN.

11 - PACKAGING MEETS GS-14-920 LEAD FREE LABELING SPECIFICATION.

A

B

B

C

C

D

D



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	title ZipLine R/A REC ASSY 6 PR, 12 IMLA, 1.8MM PITCH, 21.6MM	dwg no 10076209	Rev. A
	catalog no -	CUSTOMER	sheet 3 of 3

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